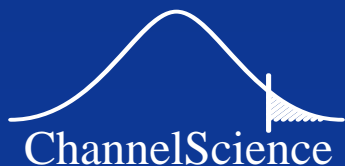




Session 302-F (OPEN)
Panel Discussion of
Intel/Micron 3D XPoint Announcement

Thursday August 13, 2015
9:45-10:50AM



Slide 1

Audio-Visual Sponsor





Chuck Sobey

ChannelScience

Established 1996

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matched to the physics of new storage technologies

Current focus: Spintronics and 3D storage

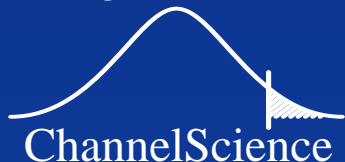
Please contact me at csobey@ChannelScience.com or 972-814-3441.

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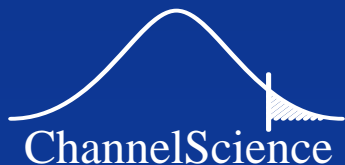
Session 302-F: 3D XPoint

Tom Coughlin, President, Coughlin and Associates

Jim Handy, Director/Chief Analyst, Objective Analysis

Dave Eggleston, Principal, Intuitive Cognition Consulting

Audience Participation



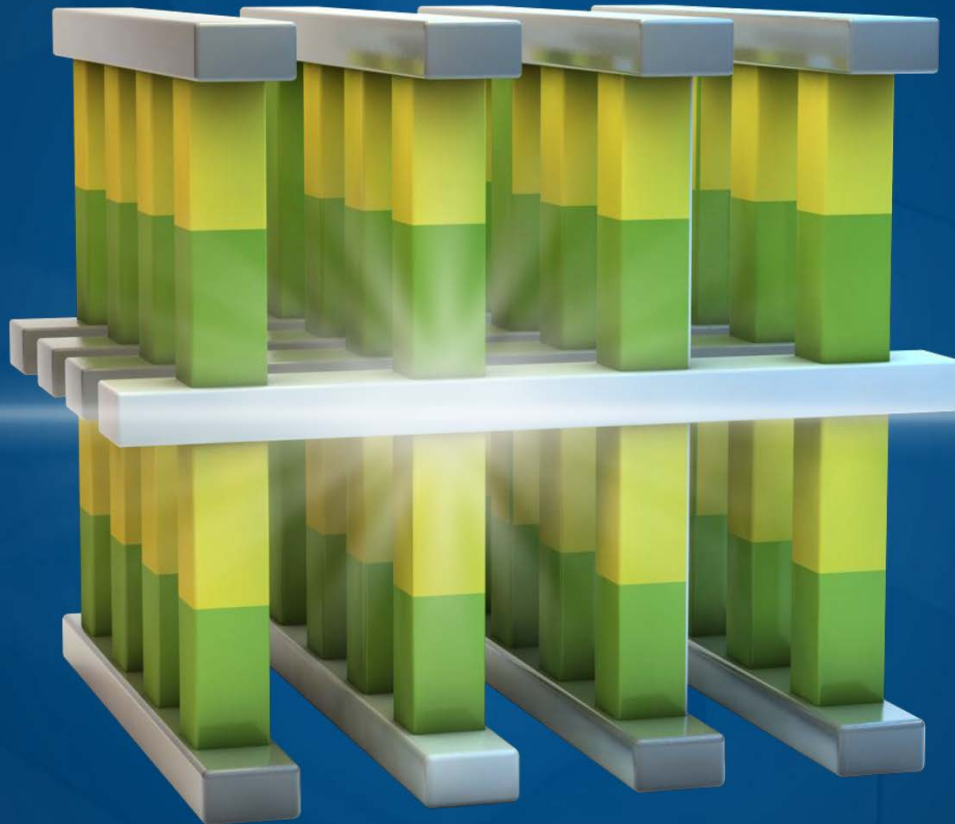
Slide 3

Audio-Visual Sponsor



Intel and Micron Announced 3D XPoint NVM on July 28, 2015

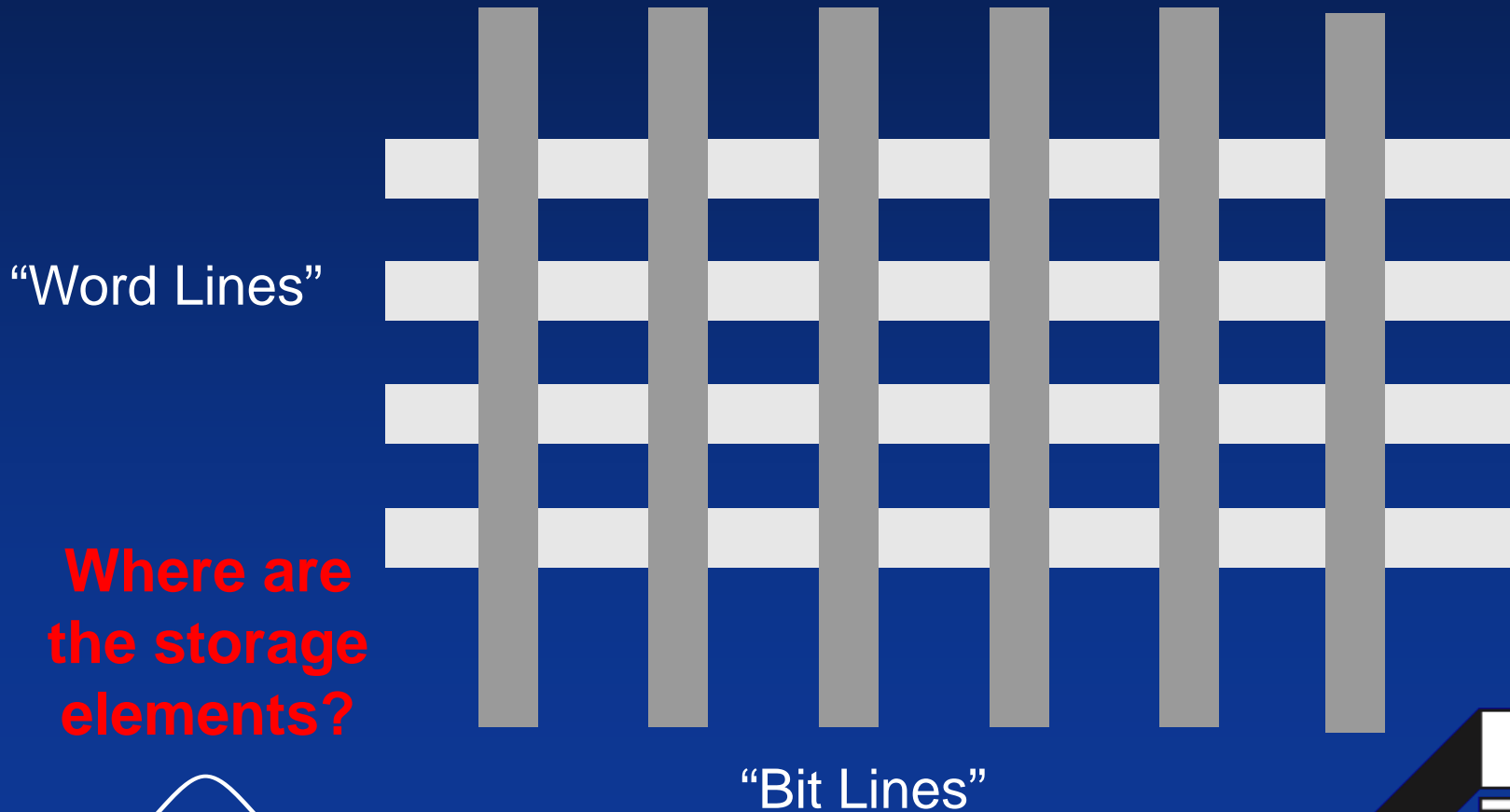
WHAT IS 3D XPOINT™?



Source: Intel / Micron

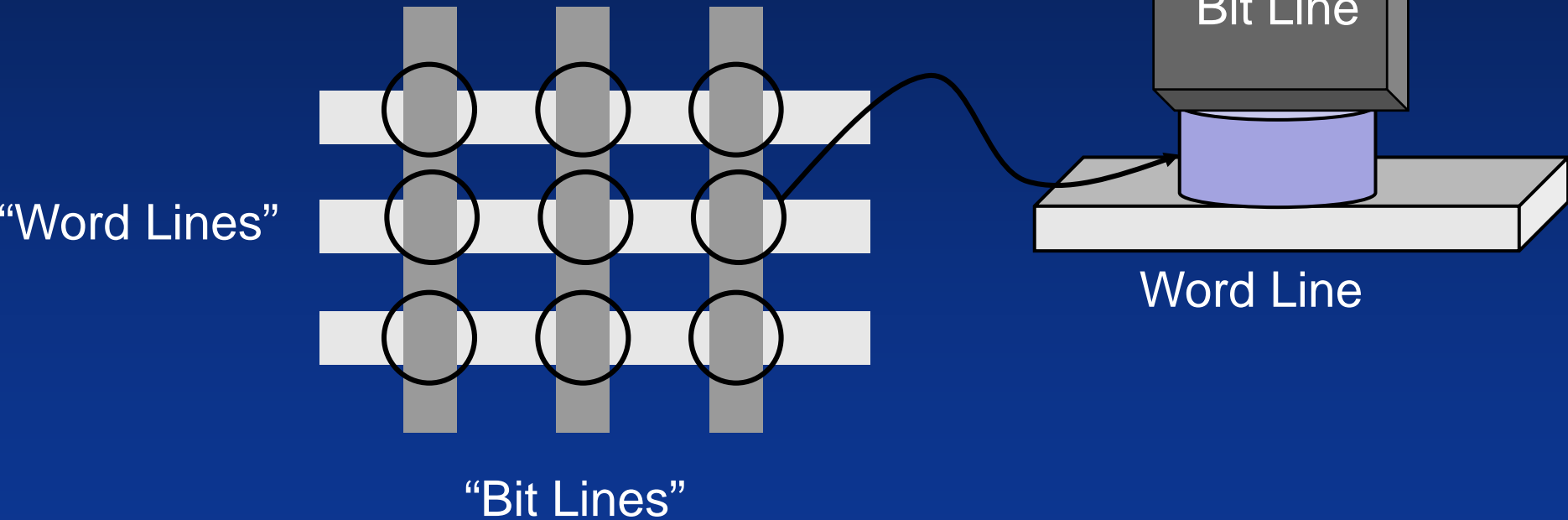
“XPoint” – Cross-Point Array (Cross-Bar Array)

The simplest structure

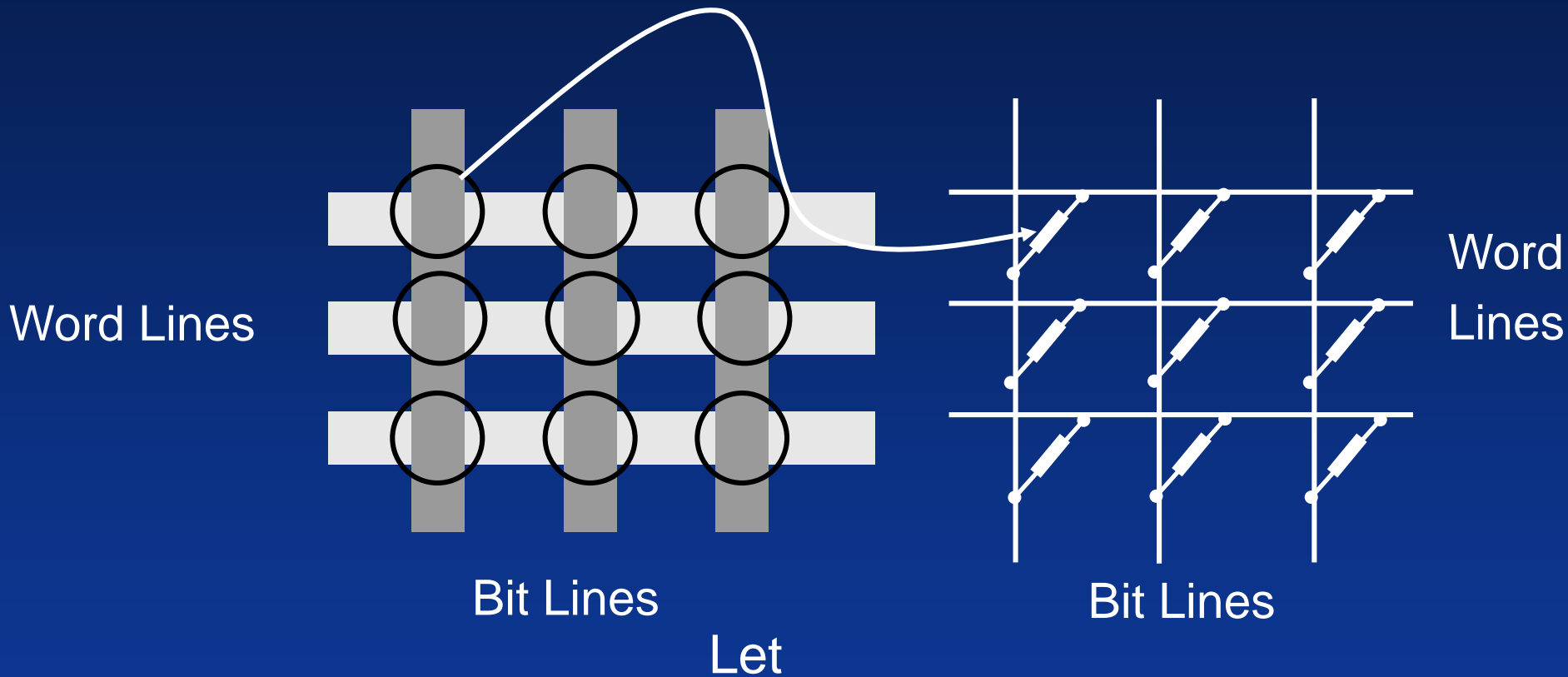


Storage Elements in a Cross-Point Array

The smallest structure: Storage element is at the intersection of the word and bit lines



Schematic of Cross-Point Array



Low resistance = 1

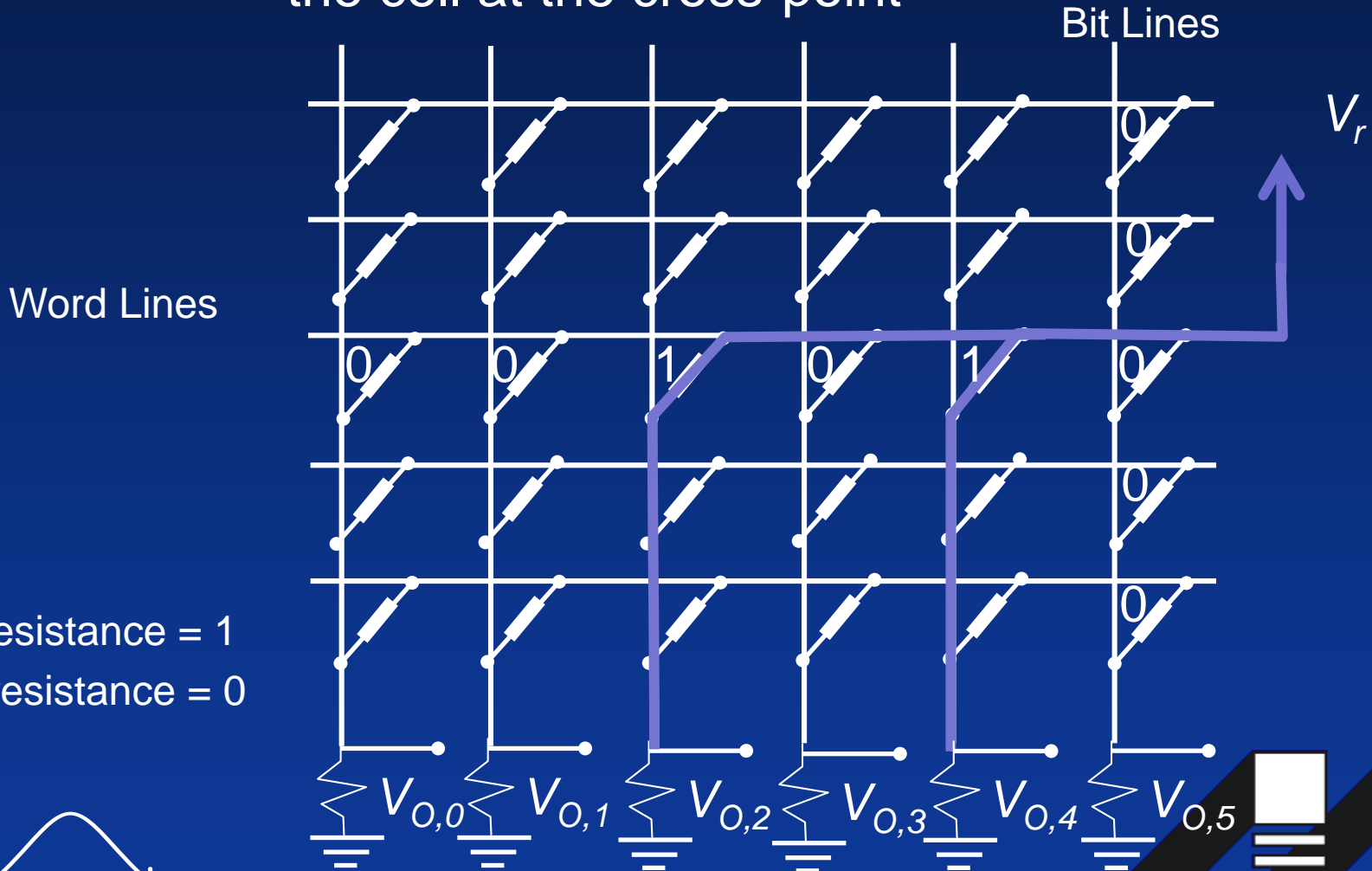
High resistance = 0

Source: KnowledgeTek SSD Class

Audio-Visual Sponsor

Reading Cells

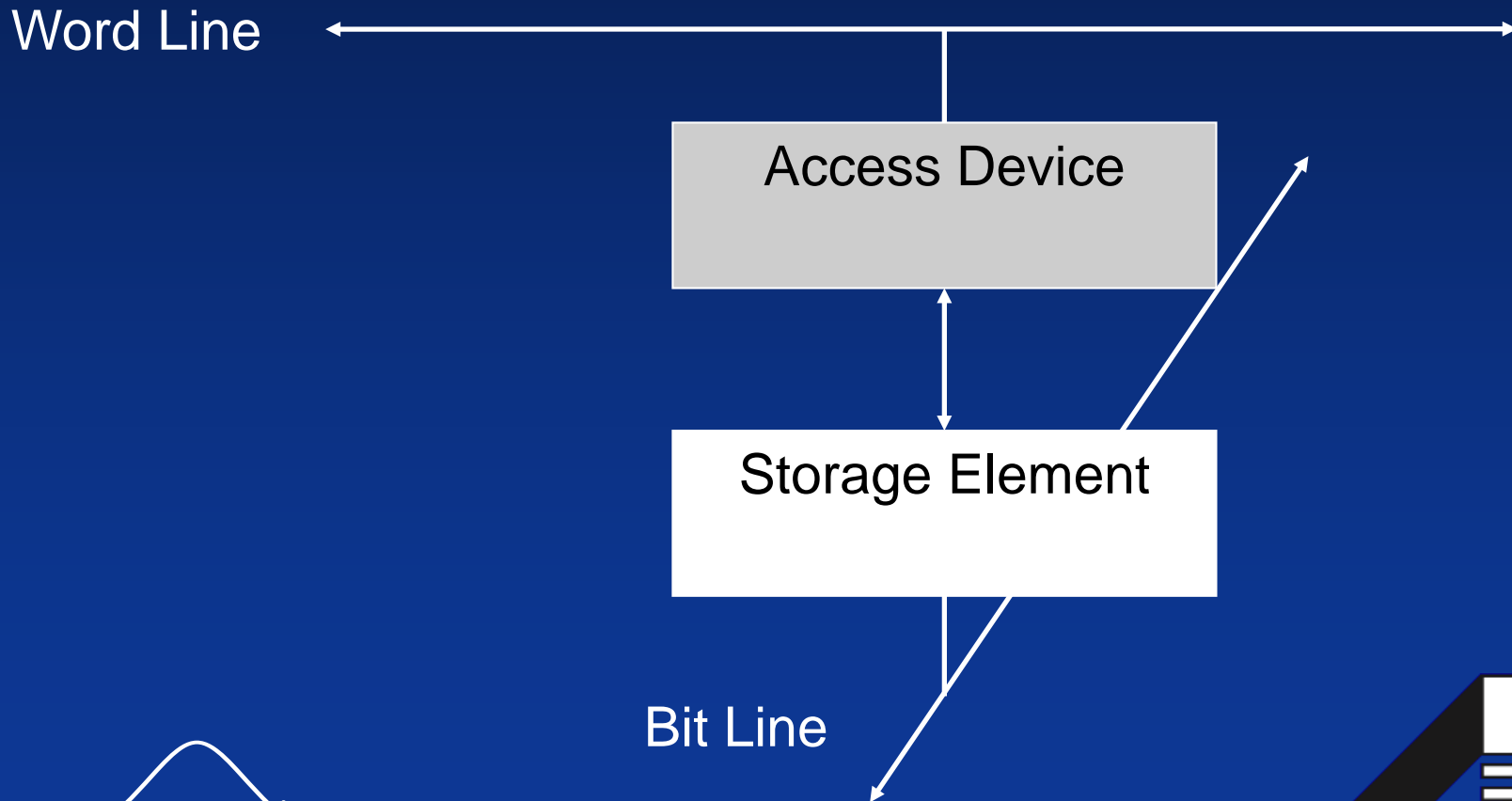
Current flow depends on the resistance value of the cell at the cross-point



Block Sneak Currents: Access Device (AD)

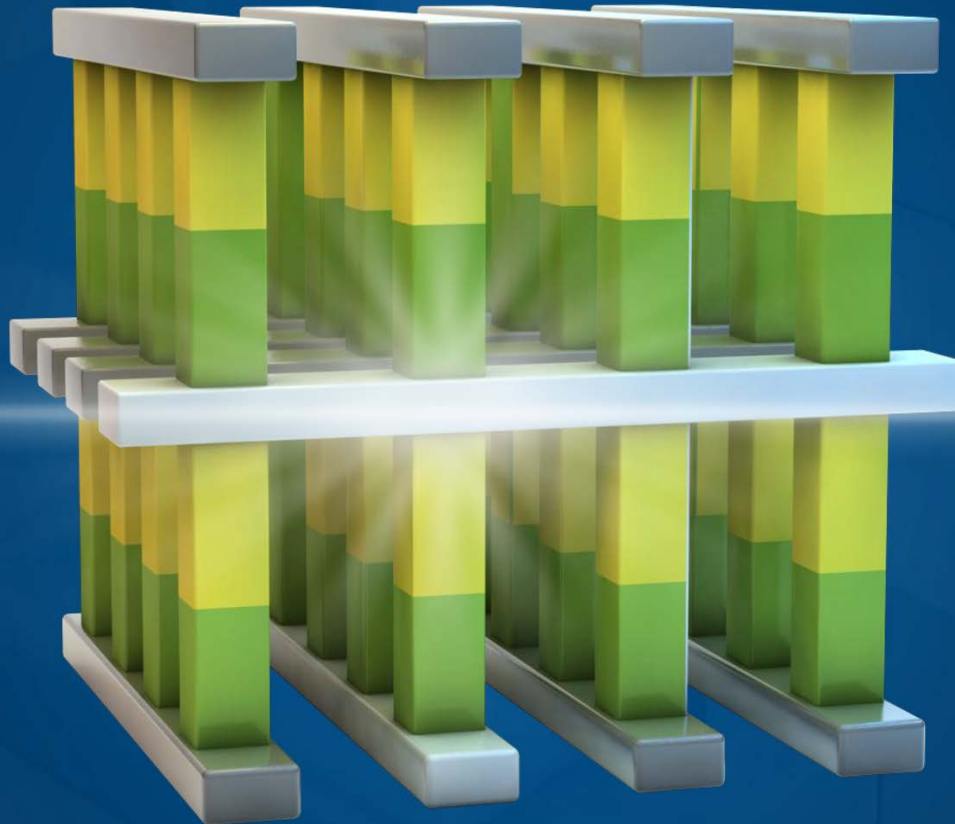
Make current only flow one way: Diodes

Make certain low-resistance cells are OFF: Transistors or other devices
(for programing and erasing)



Intel and Micron Announced 3D XPoint NVM on July 28, 2015

WHAT IS 3D XPOINT™?



Source: Intel / Micron

Do We Need A New Memory Layer?

Jim Handy



OBJECTIVE
ANALYSIS

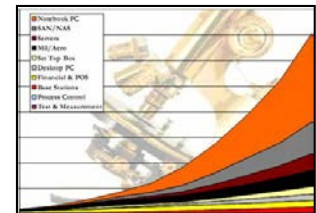
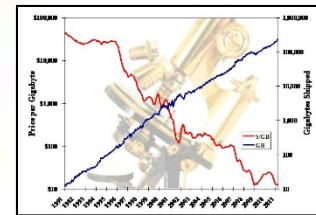
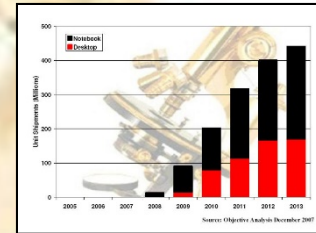
OBJECTIVE ANALYSIS



**Profound
Analysts**

**Reports &
Services**

**Custom
Consulting**



Objective Analysis

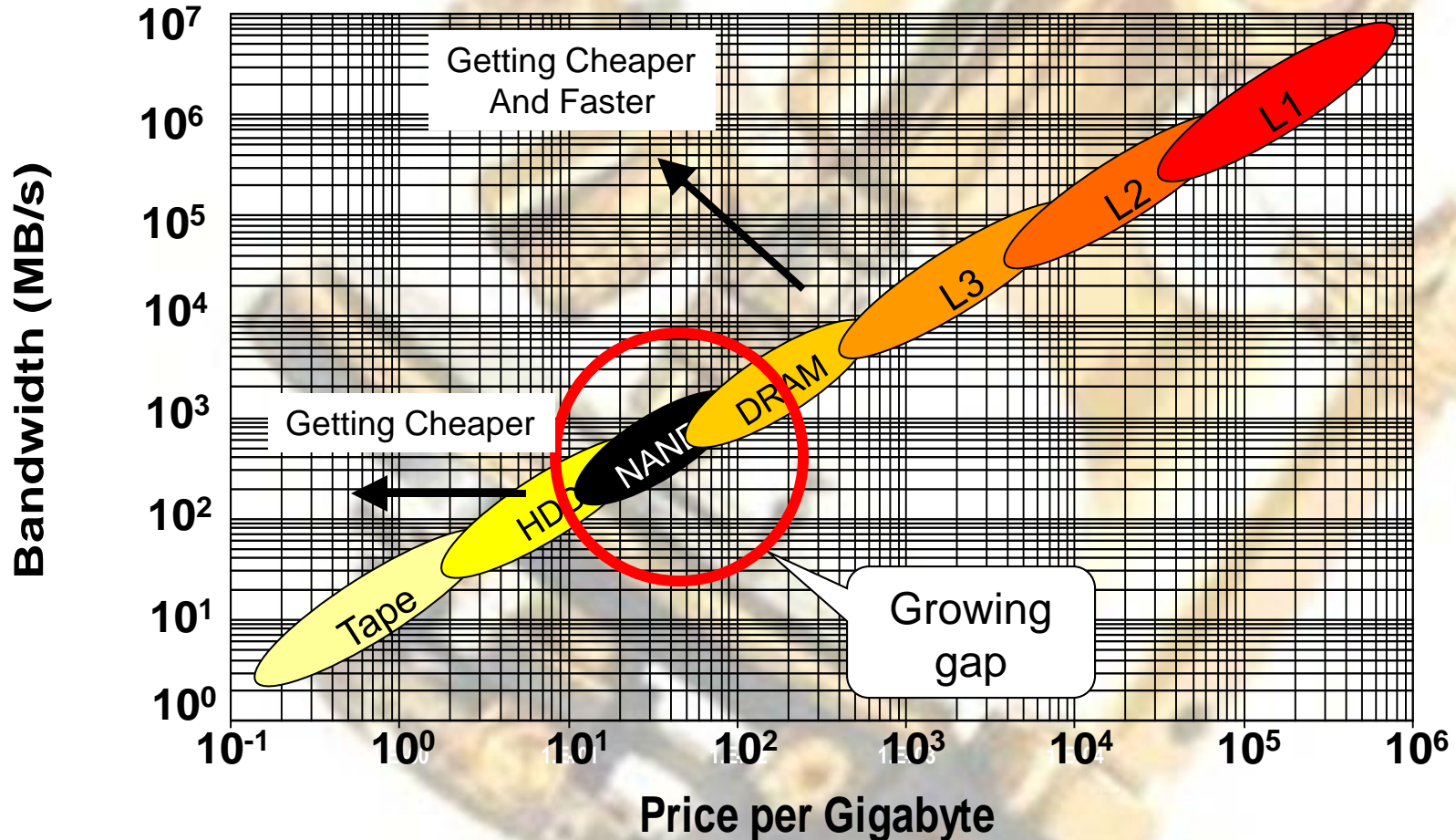
Semiconductor Forecast Accuracy

| Year | Forecast | Actual |
|-------------|------------------------------|--------|
| <u>2008</u> | Zero growth at best. | -3% |
| <u>2009</u> | Growth in the mid teens | -9% |
| <u>2010</u> | Should approach 30% | 32% |
| <u>2011</u> | Muted revenue growth: 5% | 0% |
| <u>2012</u> | Revenues drop as much as -5% | -2.7% |
| <u>2013</u> | Revenues increase nearly 10% | 4.9% |
| <u>2014</u> | Revenues up 20%+ | 9.9% |
| <u>2015</u> | Revenues up ~10% | TBD |



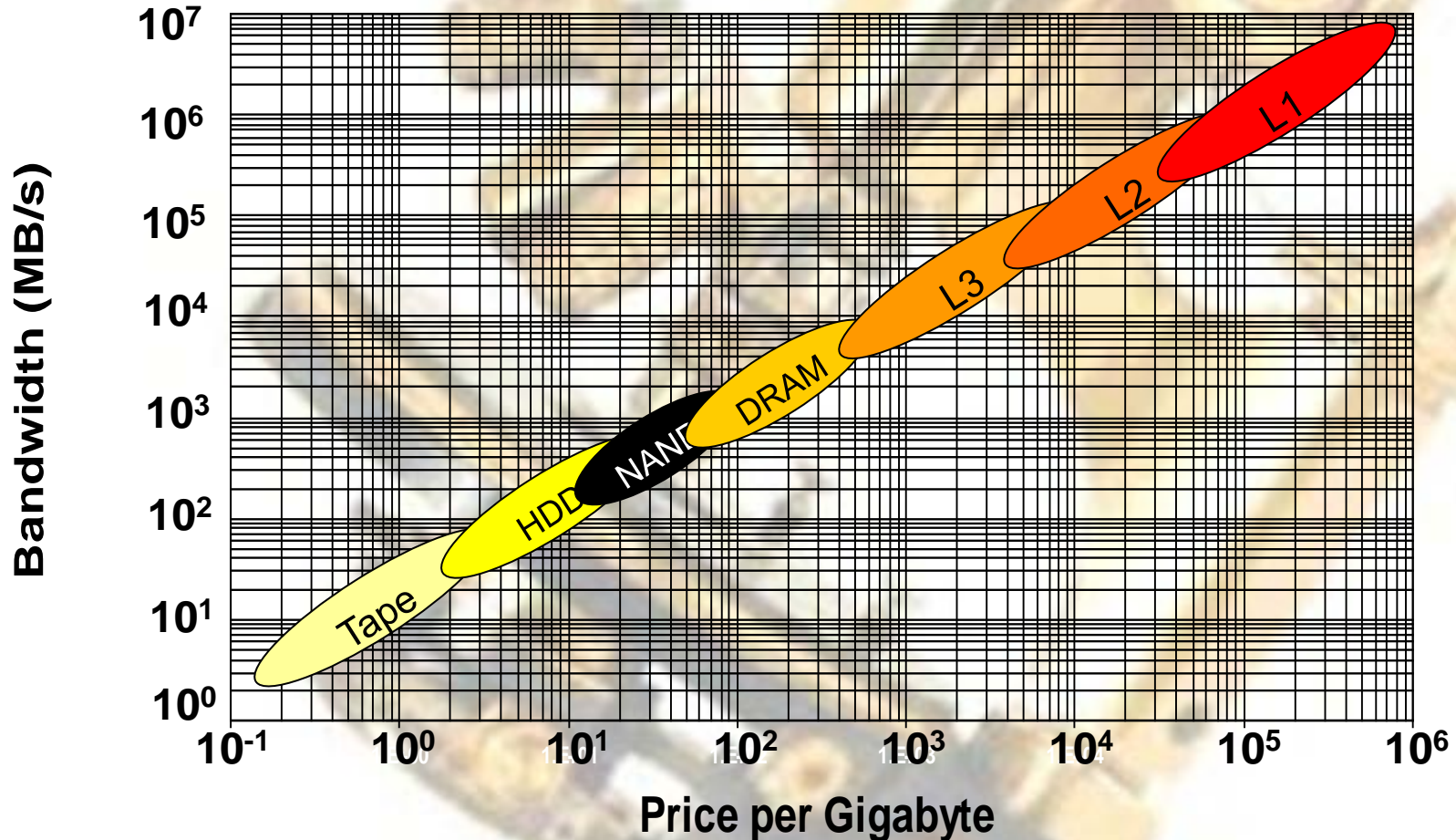
Why Add A Layer?

The DRAM/HDD Speed Gap



From: ***Solid State Drives in the Enterprise***

The DRAM/HDD Speed Gap



From: ***Solid State Drives in the Enterprise***



Will This Be Difficult?

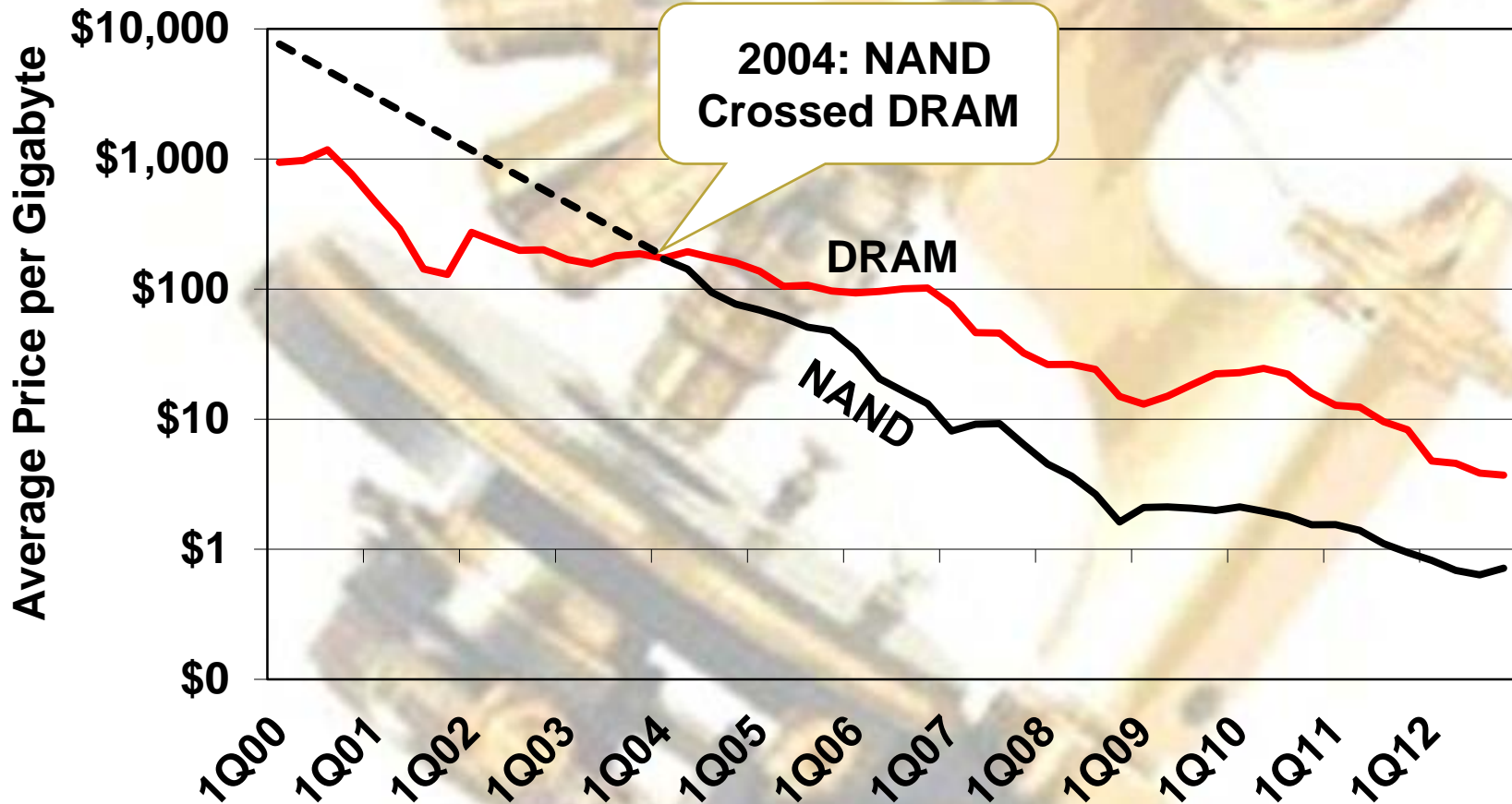
A New Memory Layer Needs A Lot Of Support

- Will require a new bus
 - DDR doesn't support variable access times
- Will require new O/S support
 - Cache management?
 - Memory management?
- Persistence will require application support
 - SNIA and others working on this
 - Some instruction support now in Intel specs



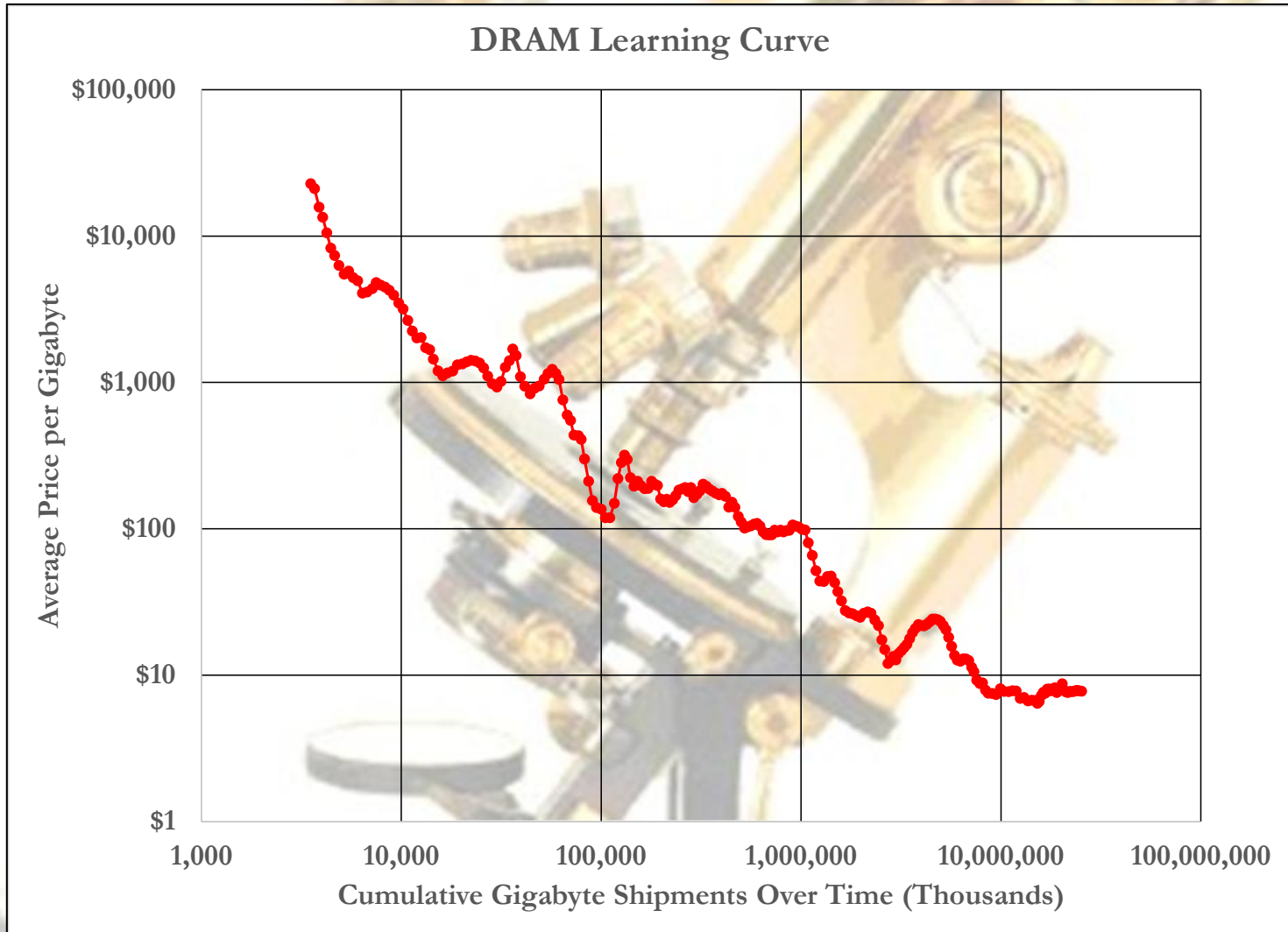
The Cost Issue

Cost Brought Flash Into Computing



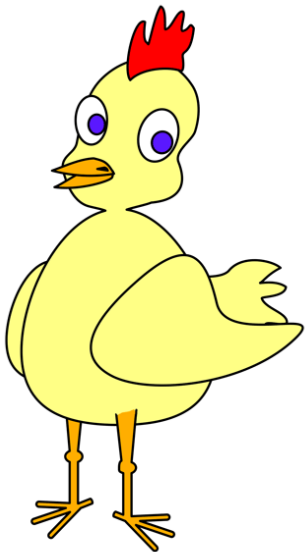
From: *Hybrid Drives: How, Why, & When?*

Volume Brings Costs Down



A Chicken & Egg Problem

- 3D XPoint will be sell in volume once it's priced lower than DRAM
- 3D XPoint prices will fall below DRAM once the volume is high enough



Summary



- New layer necessary... eventually!
 - 3D XPoint shows promise
- Lots of support will be required
 - Hardware, software, standards
- Getting pricing below DRAM will be tough
 - Smaller die size isn't the only factor
- Don't expect big changes soon



Thank You!

Jim Handy

**OBJECTIVE
ANALYSIS**